



S = Space/Gap between signaling path and ground plane  
 W = width of signal path

- 1) Connector outline. Metalized surface, no solder stop.
- 2) Keep out area for the backside of the PCB. No traces on surface allowed.

A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

<b>Rosenberger</b>				scale: 10:1 ( )		weight[g]:		
				material:		surface[mm <sup>2</sup> ]:		
<b>vertraulich / confidential</b>				date	name			
				drawn	17.08.2012	T_Oberhauser		
				check	24.09.2019	F_Tatzel		
				appr.	24.09.2019	F_Reiner		
				dimensioning incl. plating				
c00	19-1809	A_Ploetz	24.09.2019	Size ISO 14405 (E) Tolerancing ISO 8015				
b00	16-0045	B_Zimmerle	20.01.2016					
a00	13-s080	G_Schiele	01.03.2013					
200	12-v431	T_Oberhauser	21.11.2012					
100	12-m314	T_Oberhauser	20.08.2012					
rev.	change-no	name	date	drawing-no.: MB_425		sheet: 1		
				remarks: .		of: 1		